2SD2549

Silicon NPN triple diffusion planar type

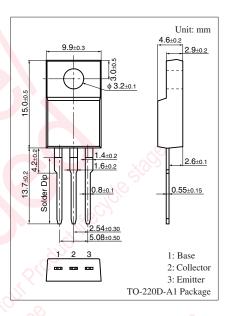
For power amplification

Features

- High forward current transfer ratio h_{FE} which has satisfactory linearity
- \bullet Low collector-emitter saturation voltage $V_{\mbox{CE(sat)}}$
- Full-pack package which can be installed to the heat sink with one screw

Absolute Maximum Ratings $T_C = 25^{\circ}C$

*	-		
Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V _{CBO}	80	V
Collector-emitter voltage (Base open)	V _{CEO}	80	V
Emitter-base voltage (Collector open)	V _{EBO}	6	v
Collector current	I _C	3	А
Peak collector current	I _{CP}	5	A
Collector power	P _C	20	W
dissipation $T_a = 25^{\circ}C$		2.0	
Junction temperature	Tj	150	°C
Storage temperature	T _{stg}	-55 to +150	S °C ⊘



Electrical Characteristics $T_c = 25^{\circ}C \pm 3^{\circ}C$

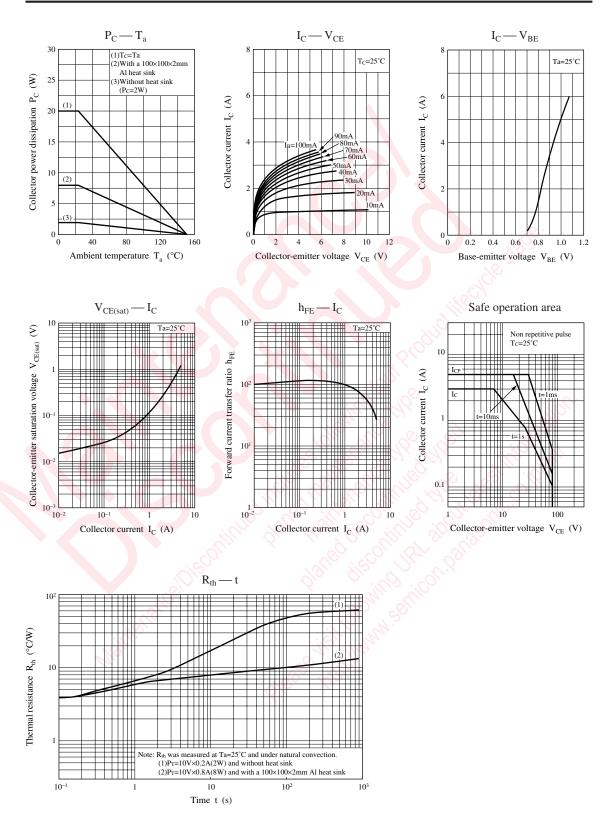
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 30 \text{ mA}, I_{\rm B} = 0$	80	0		V
Base-emitter voltage	V _{BE}	$V_{CE} = 4 V, I_C = 3 A$	20		1.8	V
Collector-emitter cutoff current (E-B short)	I _{CES}	$V_{CE} = 70 V, V_{BE} = 0$			100	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = 70 \text{ V}, I_B = 0$			100	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 6 V, I_C = 0$			1	mA
Forward current transfer ratio	h _{FE1} *	$V_{CE} = 4 V, I_C = 1 A$	70		250	
	h _{FE2}	$V_{CE} = 4 V, I_C = 3 A$	10			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = 3$ A, $I_{\rm B} = 0.375$ A			0.7	V
Transition frequency	f _T	$V_{CE} = 10 \text{ V}, I_{C} = 0.5 \text{ A}, f = 10 \text{ MHz}$		30		MHz
Turn-on time	t _{on}	$I_C = 1 A, I_{B1} = 0.1 A, I_{B2} = -0.1 A$			0.5	μs
Storage time	t _{stg}	$V_{CC} = 50 V$			4.5	μs
Fall time	t _f				0.5	μs

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	Q	Р
h _{FE1}	70 to 150	120 to 250

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